

AMENDMENTS

In th Sp cification

At p. 1, before the "Technical Field" section, insert,

--RELATED PATENT DATA

AI
09976624-10200
This patent resulted from a continuation application of U.S. Patent Application Serial Number 09/115,335 filed on July 14, 1998 which is a divisional application of U.S. Patent Application Serial Number 08/947,847 filed on October 9, 1997.--.

At p. 38, replace the abstract with,

-- ABSTRACT OF THE DISCLOSURE

AB
Methods of forming insulating materials between conductive elements include forming a material adjacent a conductive electrical component comprising: partially vaporizing a mass to form a matrix adjacent the conductive electrical component, the matrix having at least one void within it. Other methods include forming a material between a pair of conductive electrical components comprising: forming a pair of conductive electrical components within a mass and separated by an expanse of the mass; forming at least one support member within the expanse of the mass, the support member not comprising a conductive interconnect; and vaporizing the expanse of the mass to a degree effective to form at least one void between the support member and each of the pair of conductive electrical components. Some embodiments